

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claim 15 and amend claim 14 as follows:

Listing of Claims:

14. (Three Times Amended) A method for stopping polishing of a substrate at a desired endpoint, comprising:

monitoring a characteristic of a polishing component indicative of material being removed from a planarized surface of the substrate, wherein the polishing component comprises byproducts produced by polishing the substrate and the characteristic is an emission spectrum of the byproducts, and wherein monitoring a characteristic comprises analyzing the emission spectrum; and

stopping removal of material from the substrate when the characteristic of the polishing component that is monitored indicates the material being removed from the planarized surface is at the desired endpoint of the substrate.